

Title (en)

COMPOSITION WITH THERMALLY-TREATED SILICA FILLER FOR PERFORMANCE ENHANCEMENT

Title (de)

ZUSAMMENSETZUNG MIT THERMISCH BEHANDELTEM SILICIUMDIOXIDFÜLLSTOFF ZUR LEISTUNGSSTEIGERUNG

Title (fr)

COMPOSITION CONTENANT UNE CHARGE DE SILICE TRAITÉE THERMIQUEMENT POUR UNE AMÉLIORATION DE L'EFFICACITÉ

Publication

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Application

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Abstract (en)

[origin: WO2008057931A1] A curable composition comprising a curable resin and a thermally-treated silica filler, when used as an underfill material in semiconductor packages provides improved flow behavior, reduction in CTE, and enhancement of modulus, leading to reduced warpage. In one embodiment, the curable composition comprises (a) a thermally treated silica filler, (b) a curable resin (c) an initiator, and (d) optionally, adhesion promoters and/or wetting agents. The curable resins can be cyanate ester resins, epoxy resins, maleimide resins, or acrylate or methacrylate resins.

IPC 8 full level

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